

Title (en)

CONNECTION OF HEAT PUMPS AND A METHOD OF CONTROLLING HEAT PUMPS OF THIS CONNECTION

Title (de)

VERBINDUNG VON WÄRMEPUMPEN UND VERFAHREN ZUR STEUERUNG VON WÄRMEPUMPEN DIESER VERBINDUNG

Title (fr)

CONNEXION DE POMPES À CHALEUR ET PROCÉDÉ DE COMMANDE DE POMPES À CHALEUR DE CETTE CONNEXION

Publication

**EP 4375589 A1 20240529 (EN)**

Application

**EP 23209716 A 20231114**

Priority

CZ 2022492 A 20221122

Abstract (en)

The invention discloses a novel connection of heat pumps (1) having primary fluid circuits (2) in a common fluid circuit (3) to form an efficient source of heat or cold. The heat pumps (1) are connected to the common fluid circuit (3) by the primary fluid circuits (2), and a temperature sensor (5) is installed before and after each connection of the primary fluid circuit (2) to the common fluid circuit (3). The operation of the heat pumps (1) is controlled by a controller (6) according to the sensed temperature from the temperature sensors (5).

IPC 8 full level

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CPC (source: CZ EP)

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Citation (search report)

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